

General Description

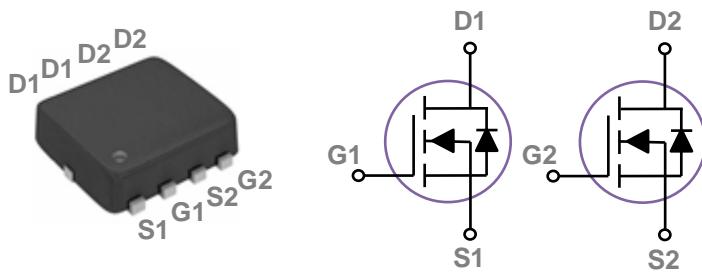
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

| BVDSS | RDS(ON) | ID |
|-------|---------|------|
| 100V | 200mΩ | 7.8A |

Features

- 100V, 7.8A, RDS(ON) = 200mΩ @ VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

PPAK3X3 Dual Pin Configuration



Applications

- Networking
- Load switch
- LED applications

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Rating | Units |
|------------------|--|------------|-------|
| V _{DS} | Drain-Source Voltage | 100 | V |
| V _{Gs} | Gate-Source Voltage | ±20 | V |
| I _D | Drain Current – Continuous ($T_c=25^\circ\text{C}$) | 7.8 | A |
| | Drain Current – Continuous ($T_c=100^\circ\text{C}$) | 4.9 | A |
| I _{DM} | Drain Current – Pulsed ¹ | 31.2 | A |
| P _D | Power Dissipation ($T_c=25^\circ\text{C}$) | 27.1 | W |
| | Power Dissipation – Derate above 25°C | 0.21 | W/°C |
| T _{STG} | Storage Temperature Range | -55 to 150 | °C |
| T _J | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Characteristics

| Symbol | Parameter | Typ. | Max. | Unit |
|------------------|--|------|------|------|
| R _{θJA} | Thermal Resistance Junction to ambient | --- | 62 | °C/W |
| R _{θJC} | Thermal Resistance Junction to Case | --- | 4.6 | °C/W |

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)
Off Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|--|--|--|------|------|-----------|---------------------------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$ | 100 | --- | --- | V |
| $\Delta \text{BV}_{\text{DSS}}/\Delta T_J$ | BV_{DSS} Temperature Coefficient | Reference to 25°C , $I_D=1\text{mA}$ | --- | 0.10 | --- | $\text{V}/^\circ\text{C}$ |
| $I_{\text{DS}}^{\text{SS}}$ | Drain-Source Leakage Current | $V_{\text{DS}}=100\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$ | --- | --- | 1 | μA |
| | | $V_{\text{DS}}=80\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$ | --- | --- | 10 | μA |
| I_{GSS} | Gate-Source Leakage Current | $V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$ | --- | --- | ± 100 | nA |

On Characteristics

| | | | | | | |
|----------------------------|--|--|-----|-----|-----|----------------------------|
| $R_{\text{DS(ON)}}$ | Static Drain-Source On-Resistance ² | $V_{\text{GS}}=10\text{V}$, $I_D=4\text{A}$ | --- | 160 | 200 | $\text{m}\Omega$ |
| | | $V_{\text{GS}}=4.5\text{V}$, $I_D=2\text{A}$ | --- | 170 | 210 | $\text{m}\Omega$ |
| $V_{\text{GS(th)}}$ | Gate Threshold Voltage | $V_{\text{GS}}=V_{\text{DS}}$, $I_D = 250\mu\text{A}$ | 1.2 | 1.8 | 2.5 | V |
| $\Delta V_{\text{GS(th)}}$ | $V_{\text{GS(th)}}$ Temperature Coefficient | | --- | -4 | --- | $\text{mV}/^\circ\text{C}$ |
| g_{fs} | Forward Transconductance | $V_{\text{DS}}=10\text{V}$, $I_D=1\text{A}$ | --- | 5 | --- | S |

Dynamic and switching Characteristics

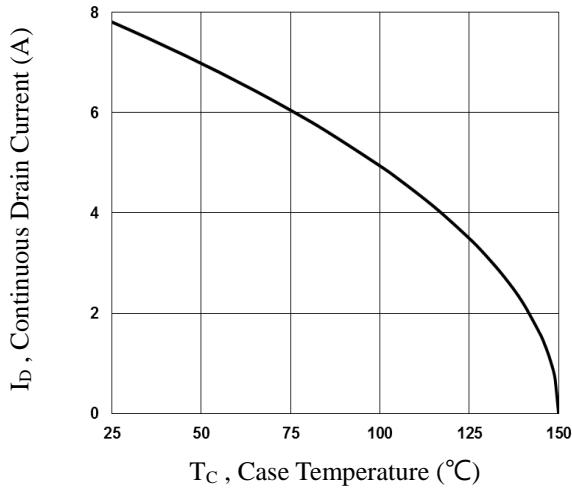
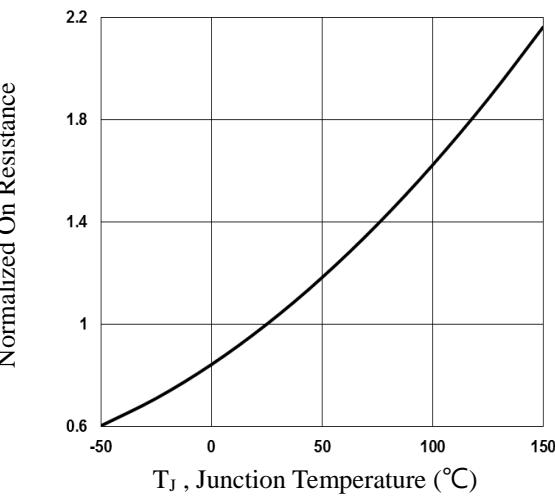
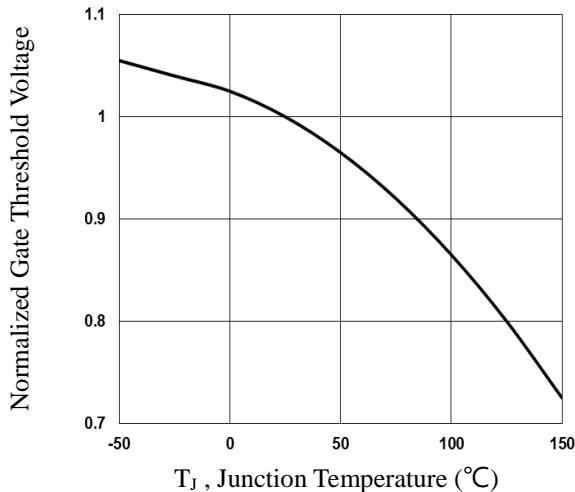
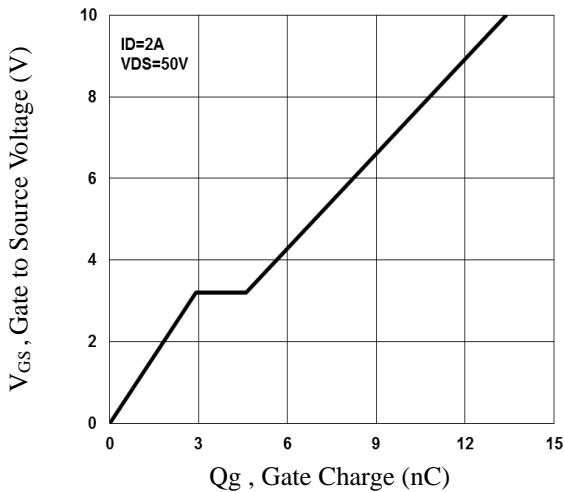
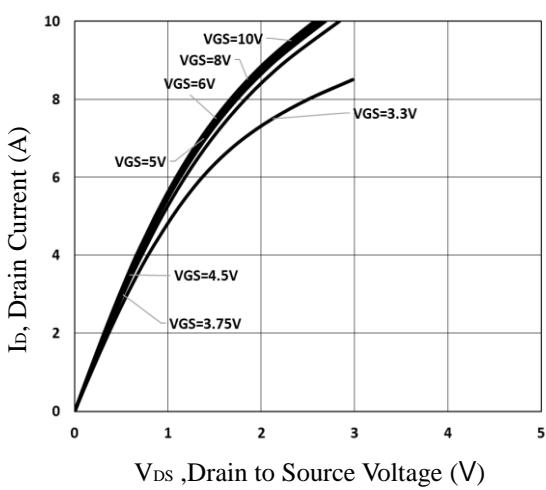
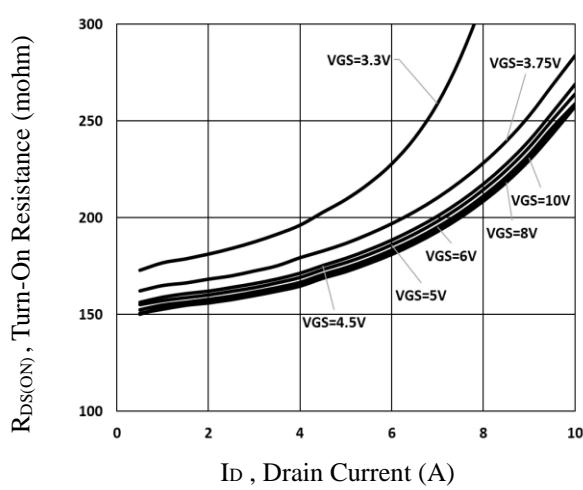
| | | | | | | |
|---------------------|-------------------------------------|---|-----|------|------|----------|
| Q_g | Total Gate Charge ^{2, 3} | $V_{\text{DS}}=50\text{V}$, $V_{\text{GS}}=10\text{V}$, $I_D=2\text{A}$ | --- | 13.4 | 21 | nC |
| Q_{gs} | Gate-Source Charge ^{2, 3} | | --- | 2.9 | 6 | |
| Q_{gd} | Gate-Drain Charge ^{2, 3} | | --- | 1.7 | 4 | |
| $T_{\text{d(on)}}$ | Turn-On Delay Time ^{2, 3} | $V_{\text{DD}}=30\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=3.3\Omega$ | --- | 1.6 | 3 | ns |
| T_r | Rise Time ^{2, 3} | | --- | 6.6 | 13 | |
| $T_{\text{d(off)}}$ | Turn-Off Delay Time ^{2, 3} | | --- | 11.5 | 22 | |
| T_f | Fall Time ^{2, 3} | | --- | 3.6 | 7 | |
| C_{iss} | Input Capacitance | $V_{\text{DS}}=50\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$ | --- | 820 | 1190 | pF |
| C_{oss} | Output Capacitance | | --- | 35 | 55 | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 20 | 30 | |
| R_g | Gate resistance | $V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=0\text{V}$, $f=1\text{MHz}$ | --- | 1.3 | 2.6 | Ω |

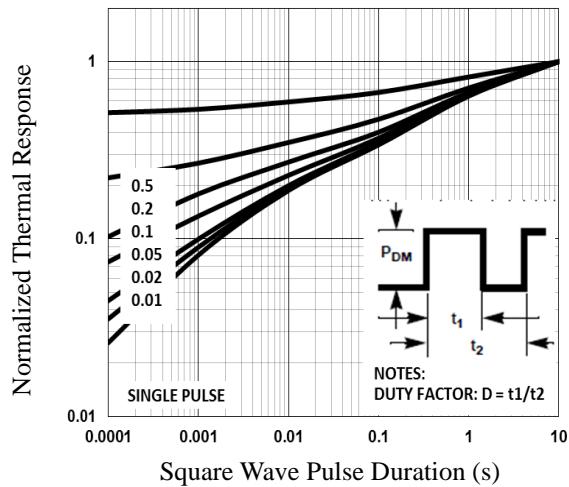
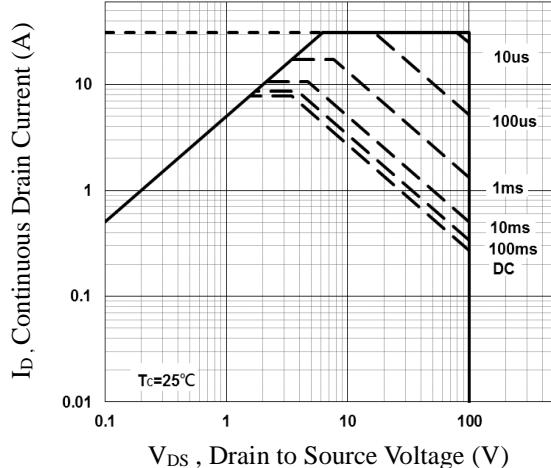
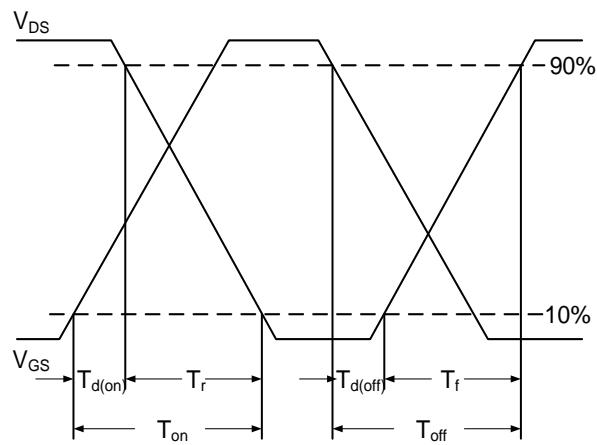
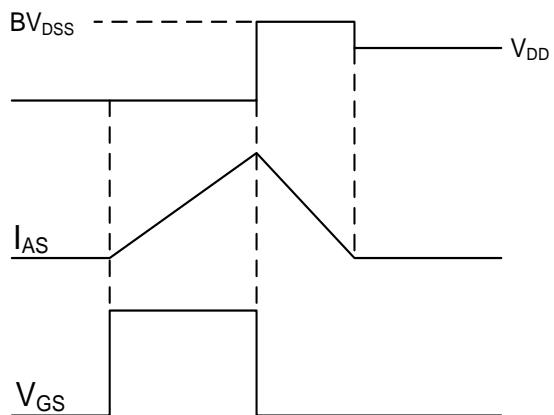
Drain-Source Diode Characteristics and Maximum Ratings

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------------|------------------------------------|--|------|------|------|------|
| I_s | Continuous Source Current | $V_G=V_D=0\text{V}$, Force Current | --- | --- | 7.8 | A |
| I_{SM} | Pulsed Source Current ² | | --- | --- | 15.6 | A |
| V_{SD} | Diode Forward Voltage ² | $V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$ | --- | --- | 1 | V |

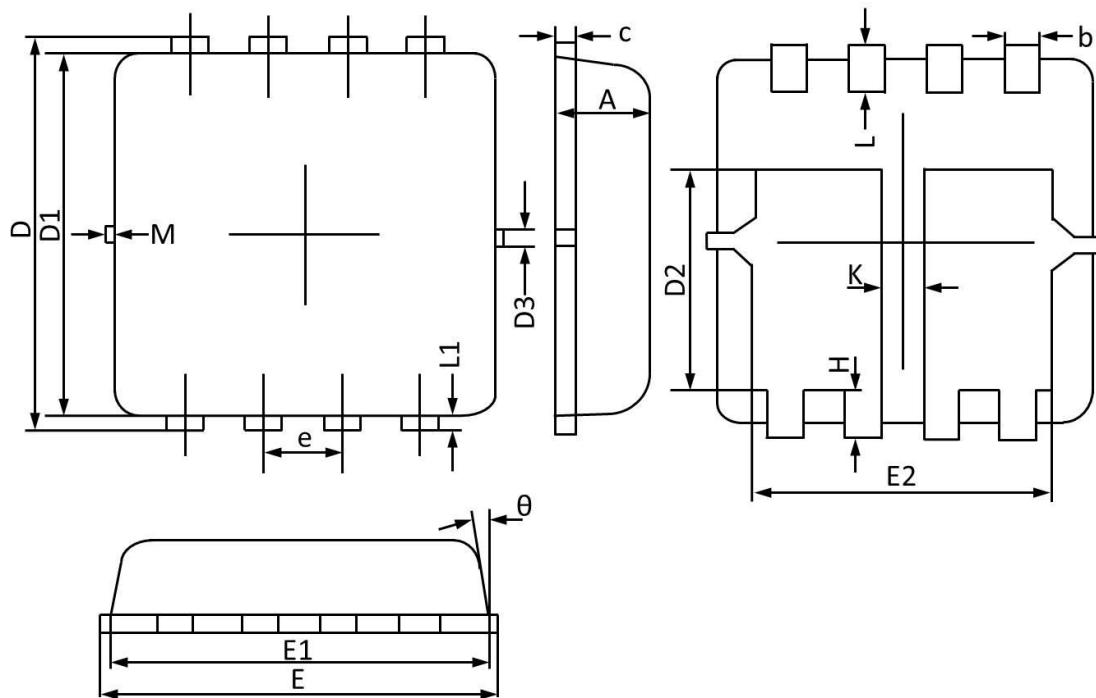
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

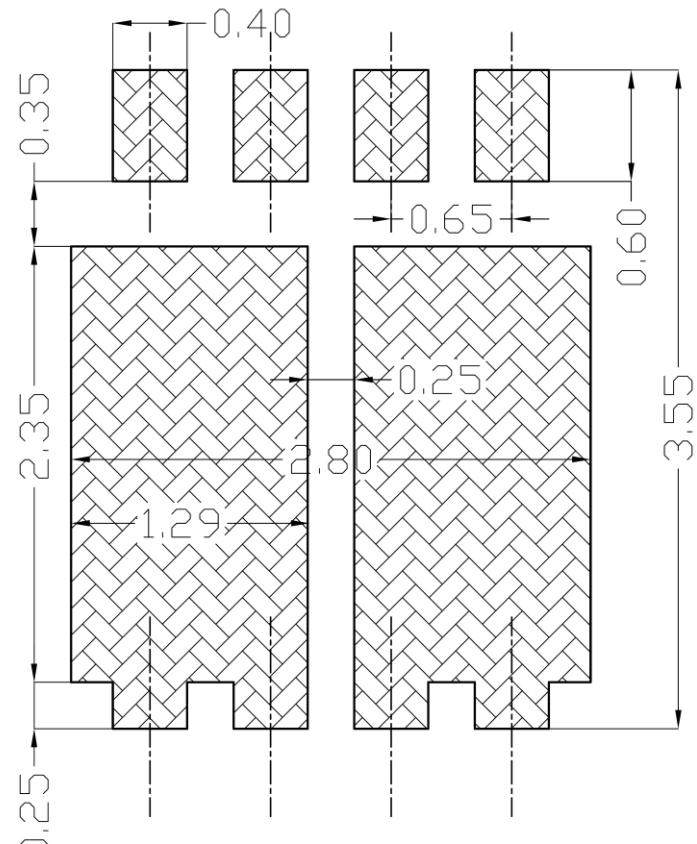

Fig.1 Continuous Drain Current vs. T_C

Fig.2 Normalized RDSON vs. T_J

Fig.3 Normalized V_{th} vs. T_J

Fig.4 Gate Charge Waveform

Fig.5 Typical Output Characteristics

Fig.6 Turn-On Resistance vs. ID


Fig.7 Normalized Transient Response

Fig.8 Maximum Safe Operation Area

Fig.9 Switching Time Waveform

Fig.10 EAS Waveform

PPAK3x3 Dual PACKAGE INFORMATION



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 0.670 | 0.880 | 0.026 | 0.035 |
| b | 0.250 | 0.350 | 0.010 | 0.014 |
| c | 0.100 | 0.250 | 0.004 | 0.010 |
| D | 3.150 | 3.550 | 0.124 | 0.140 |
| D1 | 3.000 | 3.300 | 0.118 | 0.130 |
| D2 | 1.500 | 2.000 | 0.059 | 0.079 |
| D3 | 0.130 | 0.200 | 0.005 | 0.008 |
| E | 3.100 | 3.500 | 0.122 | 0.138 |
| E1 | 3.000 | 3.200 | 0.118 | 0.126 |
| E2 | 2.350 | 2.600 | 0.093 | 0.102 |
| e | 0.650 BSC | | 0.026 BSC | |
| H | 0.300 | 0.500 | 0.012 | 0.020 |
| L | 0.300 | 0.500 | 0.012 | 0.020 |
| L1 | 0.130 REF | | 0.005 REF | |
| K | 0.300 REF | | 0.012 REF | |
| θ | 0° | 12° | 0° | 12° |
| M | 0.150 REF | | 0.006 REF | |

PPAK3X3 Dual RECOMMENDED LAND PATTERN

unit : mm